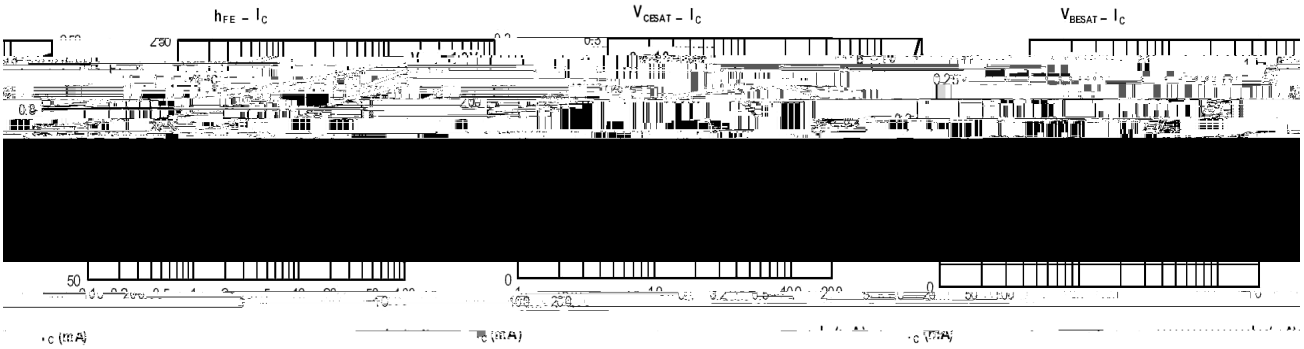
MMBT3906

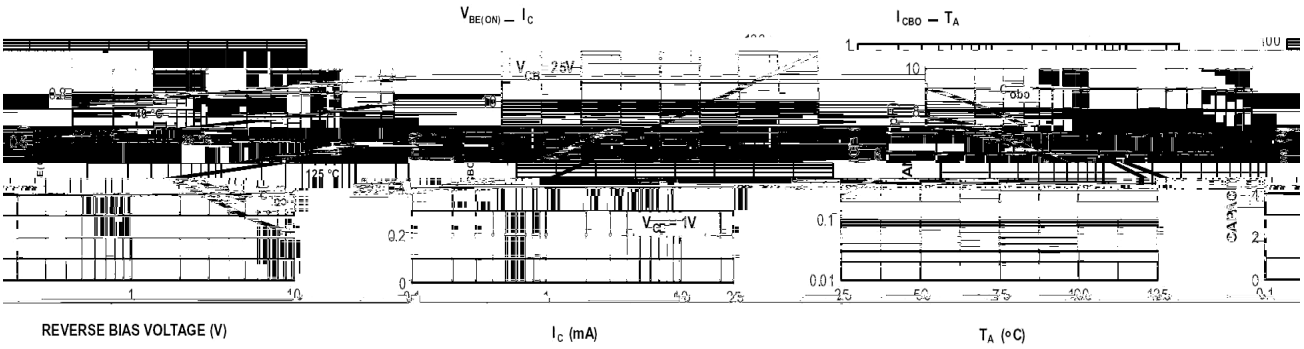
i j Parameter	k l Symbol	j m Rating	n o Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current	I_C	-200	mA
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_j	150	℃
Storage Temperature Range	T_{stg}	-55～150	℃

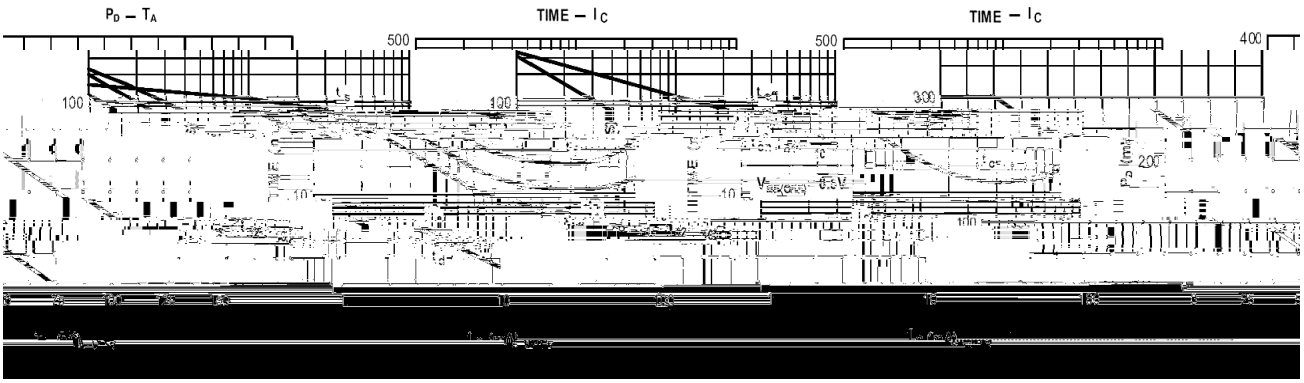
i j Parameter	k l Symbol	p q r s Test Conditions	t u m Min	v w m T

i j

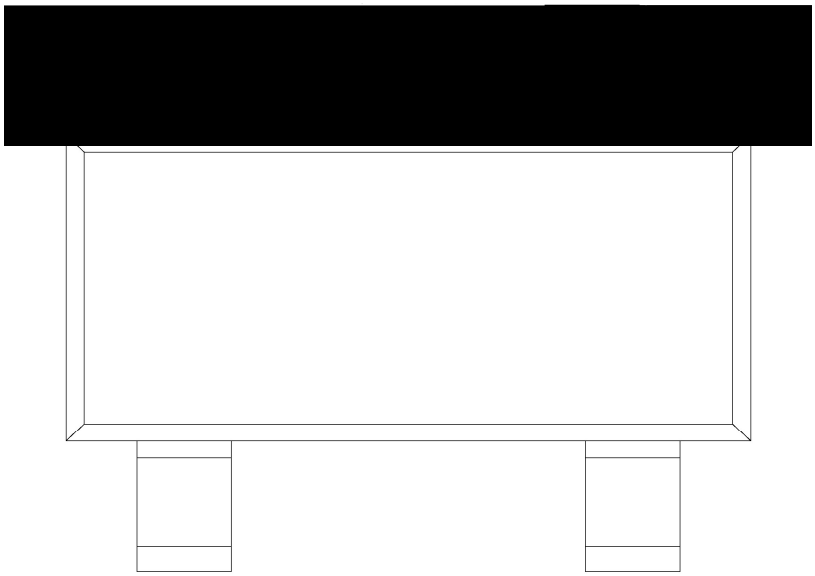
/ Electrical Characteristic Curve



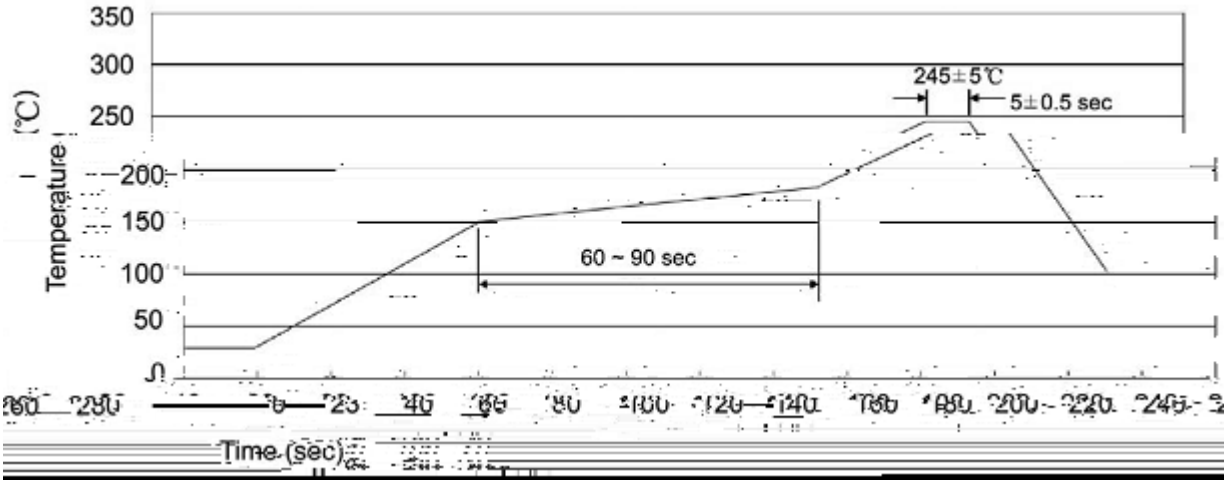




/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;
1.Preheating:25~150 , Time:60~90sec.

2 245±5 5±0.5sec;
2.Peak Temp.:245±5 , Duration:5±0.5sec.

3 2 10 /sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type !	Units " # $	Dimension " % & (unit ' mm^3)